



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

November 24, 2010

Applicants: Toshihiro TAI et al  
For: PLATED RESIN MOLDED ARTICLES  
Serial No.: 10/586 378 Group: 1787  
Confirmation No.: 2951  
Filed: July 14, 2006 Examiner: Kruer  
International Application No.: PCT/JP2005/002827  
International Filing Date: February 16, 2005  
Atty. Docket No.: 3400.P1434US

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE**

Sir:

In response to the Office Action dated October 1, 2010,  
please amend the above-identified application as follows:

(Please see following pages.)

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**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being  
deposited with the United States Postal Service with  
sufficient postage as first class mail in an envelope  
addressed to: Commissioner for Patents, P.O. Box 1450,  
Alexandria, VA 22313-1450, on November 24, 2010.

  
Terrance F. Chapman